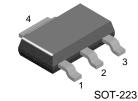


BCP69

PNP General Purpose Amplifier

- This device is designed for general purpose medium power amplifiers and switches requiring collector currents to 1.0A.
- Sourced from Process 77.



1. Base 2.4. Collector 3. Emitter

Absolute Maximum Ratings * T_C=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V_{CEO}	Collector-Emitter Voltage	-20	V
V _{CBO}	Collector-Base Voltage	-30	V
V _{EBO}	Emitter-Base Voltage	-5.0	V
I _C	Collector current - Continuous	-1.5	Α
T _J , T _{stq}	Junction and Storage Temperature	-55 ~ +150	°C

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are baseed on a maximum junction temperature of 150 degrees C.
 These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Electrical Characteristics T_C=25°C unless otherwise noted

Parameter	Test Condition	Min.	Max.	Units
Off Characteristics				
Collector-Emitter Breakdown Voltage *	$I_C = -10 \text{mA}, I_B = 0$	-20		V
Collector-Base Breakdown Voltage	$I_C = -1.0 \text{mA}, I_E = 0$	-30		V
Emitter-Base Breakdown Voltage	$I_E = -100 \mu A, I_C = 0$	-5.0		V
Collector Cutoff Current	$V_{CB} = -25V, I_{E} = 0$		-10	μΑ
Emitter Cutoff Current	$V_{EB} = -5.0V, I_{C} = 0$		-10	μΑ
eristics *				
DC Current Gain	$I_C = -5 \text{mA}, V_{CE} = -1.0 \text{V}$	50		
	$I_C = -500 \text{mA}, V_{CE} = -1.0 \text{V}$	85	375	
	$I_C = -1.0A, V_{CE} = -1.0V$	60		
Collector-Emitter Saturation Voltage	I _C = -1.0A, I _B = -100mA		-0.5	V
Base-Emitter On Voltage	I _C = -1.0A, V _{CE} = -1.0V		-1.0	V
I Characteristics				
Small-Signal Current Gain	$I_C = -50 \text{mA}, V_{CE} = -10 \text{V}, f = 20 \text{MHz}$	2.5		
Collector-Base Capacitance	$V_{CB} = -10V, I_E = 0, f = 1.0MHz$		30	pF
	Collector-Emitter Breakdown Voltage * Collector-Base Breakdown Voltage Emitter-Base Breakdown Voltage Collector Cutoff Current Emitter Cutoff Current eristics * DC Current Gain Collector-Emitter Saturation Voltage Base-Emitter On Voltage I Characteristics Small-Signal Current Gain		$ \begin{array}{ c c c c } \hline \textbf{Collector-Emitter Breakdown Voltage} & I_C = -10\text{mA}, I_B = 0 & -20 \\ \hline \textbf{Collector-Base Breakdown Voltage} & I_C = -1.0\text{mA}, I_E = 0 & -30 \\ \hline \textbf{Emitter-Base Breakdown Voltage} & I_E = -100\mu\text{A}, I_C = 0 & -5.0 \\ \hline \textbf{Collector Cutoff Current} & V_{CB} = -25\text{V}, I_E = 0 & -5.0 \\ \hline \textbf{Emitter Cutoff Current} & V_{EB} = -5.0\text{V}, I_C = 0 & -5.0 \\ \hline \textbf{Emitter Cutoff Current} & I_C = -500\text{mA}, V_{CE} = -1.0\text{V} & 50 \\ \hline \textbf{I}_C = -500\text{mA}, V_{CE} = -1.0\text{V} & 85 \\ \hline \textbf{I}_C = -1.0\text{A}, V_{CE} = -1.0\text{V} & 60 \\ \hline \textbf{Collector-Emitter Saturation Voltage} & I_C = -1.0\text{A}, I_B = -100\text{mA} \\ \hline \textbf{Base-Emitter On Voltage} & I_C = -1.0\text{A}, V_{CE} = -1.0\text{V} \\ \hline \textbf{Small-Signal Current Gain} & I_C = -50\text{mA}, V_{CE} = -10\text{V}, f = 20\text{MHz} & 2.5 \\ \hline \end{array} $	$ \begin{array}{ c c c c } \hline \textbf{Collector-Emitter Breakdown Voltage} & I_C = -10\text{mA}, I_B = 0 & -20 \\ \hline \textbf{Collector-Base Breakdown Voltage} & I_C = -1.0\text{mA}, I_E = 0 & -30 \\ \hline \textbf{Emitter-Base Breakdown Voltage} & I_E = -100\mu\text{A}, I_C = 0 & -5.0 \\ \hline \textbf{Collector Cutoff Current} & V_{CB} = -25\text{V}, I_E = 0 & -10 \\ \hline \textbf{Emitter Cutoff Current} & V_{EB} = -5.0\text{V}, I_C = 0 & -10 \\ \hline \textbf{eristics} & & & & & & & & & & & & & & & & & & &$

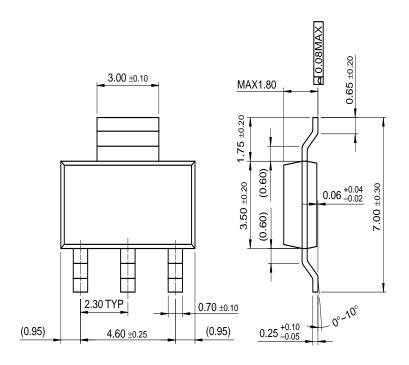
^{*} Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 1.0%

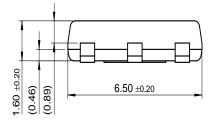
Thermal Characteristics T_A=25°C unless otherwise noted

Symbol	Parameter	Max.	Units
P_{D}	Total Device Dissipation Derate above 25°C	1.0 8.0	W mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	125	°C/W

* Device mounted on FR-4 PCB 36mm × 18mm × 1.5mm; mounting pad for the collector lead min. 6cm²

Package Dimensions





Dimensions in Millimeters

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E ² CMOS™	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	I ² C TM	OCX^{TM}	RapidConfigure™	UHC™
Across the board.	Around the world.™	OCXPro™	RapidConnect™	UltraFET [®]
The Power Franchise™		OPTOLOGIC [®]	SILENT SWITCHER®	VCX™
Programmable Ad	ctive Droop™	OPTOPLANAR™	SMART START™	

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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
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